

REMARKS

In response to the Official Action of April 18, 2005, independent claim 53 has been amended in a manner which is believed to distinguish the claim over US patent 5,986,338, Nakajima.

The Examiner at paragraph 2 of the Official Action rejects claims 53, 57, 58 and 59 as anticipated in view of Nakajima stating that with regard to claim 53, Nakajima discloses in Figures 4 and 13 an electronic component to have an electrical component (wafer 1) incorporated thereon wherein the electronic component comprises a substrate (elements 7, 9b) having at least a front substrate layer (7) for receiving the electrical component (wafer 1) and conductive vias (as indicated at numeral 10 in Figure 4) provided through the substrate (comprising elements 7, 9b) or at least a front layer (7) thereof for electrical connection to the electrical component (wafer 1) and characterized in that the electrical component further comprises grooves (25) provided in the front surface of the substrate (elements 7, 9b) with the conductive lines (conductive layer 8) being formed in the grooves (25) for electrical connection to the electrical component (wafer 1).

This analysis of Nakajima states that the conductive layer (8) is formed within grooves (25). However, a review of Figures 4 and 13 in Nakajima makes clear that the conductive layer (8) not only is within grooves (25) but extends beyond the grooves and over portions of the front surface layer (7) which in Nakajima is described as a reinforcing plate (7).

Claim 53 has been amended to specifically point out and claim that the grooves in the electronic component are provided in the front surface of the substrate with separate conductive lines which are formed completely within the grooves for electrical connection to the electrical component. This amendment to claim 53 is supported by the original figures of the present application, including Figures 1 and 2, and by the original specification, including page 12, lines 10-17 wherein it states that the grooves are filled with molybdenum (36), such as with a sputtering process which covers the entire front surface of the front layer including lands (38) between the grooves and then the excess molybdenum is removed on the lands (38) leaving metal

in the grooves.¹ As such, amended claim 53 is supported by the original specification and in view of this amendment, it is clear that the conductive lines are separate and formed completely within the grooves in a manner totally unlike the conductive layer (8) disclosed in Nakajima.

It is therefore respectfully submitted that amended claim 53 is distinguished over Nakajima.

Since claim 53 is believed to be distinguished over Nakajima, it is respectfully submitted that dependent claims 57, 58 and 59, all of which depend from claim 53, are also distinguished over Nakajima.

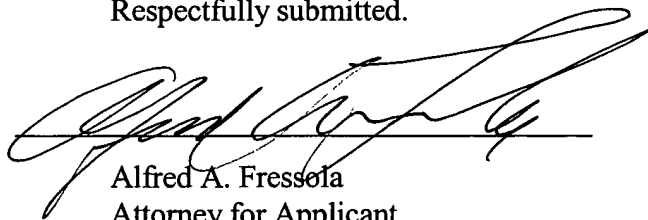
Referring now to paragraph 4 of the Official Action, it is respectfully submitted that claims 54-56 are not obvious under 35 U.S.C. §103(a) in view of Nakajima further in view of US patent 6,031,729, Berkely et al, due to the fact that claims 54-56 all ultimately depend from claim 53 which, for the reasons set forth above, are believed to be distinguished over the cited art.

In view of the foregoing, it is respectfully submitted that the present application is in condition for allowance and such action is earnestly solicited.

Respectfully submitted.

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¹ At line 4 of claim 53, the word "face" has been replaced by "surface" so that there is proper antecedent basis for the phrase "front surface" at line 10 of claim 53.